## **CSIR - Central Scientific Instruments Organization**

PR NO: CSIR-CSIO/µNOC/2024-25/FIR010302/18

Date: 02.01.2025

## **Sub: Requirement of Wafers**

There is a requirement for wafers having the following specifications:

Sl. No.	Details of Items	Quantity
1.	Borosilicate Wafer  • Dia: 4 inch • Thickness: 1000 ± 20 μm • 2-side polished • Primary flat: 32.5 mm	10 Nos
2.	Fused silica wafer • Dia: 4 inch +/- 0.2 mm • Thickness: 1000 ± 25 μm • 2-side polished TTV: < 10 μm • Primary -at: 32.50mm +/- 2.50 mm • OH content: < 300 ppm	25 Nos

**Interested firms**, who can supply the same, are requested to send their quotations through email to **ishani@csio.res.in** with CC to **sudipta@csio.res.in** and **spo@csio.res.in** on or before **13.01.2025**.

**Note:** L1 will be considered based on the total price quoted for both the above-mentioned items.

## **Other Terms & Conditions:**

- 1. **Delivery:** F.O.R. CSIO Chandigarh.
- 2. **Payment Terms:** Within 30 days after delivery of the items